

**Amendments to the Specification:**

Please replace the CROSS-REFERENCE TO RELATED APPLICATIONS section on page 1 with the following:

This application is a divisional application of U.S. Patent Application No. 10/228,906, entitled "MICROELECTRONIC DEVICES WITH IMPROVED HEAT DISSIPATION AND METHODS FOR COOLING MICROELECTRONIC DEVICES," filed August 27, 2002, now U.S. Patent No. 6,710,442, issued March 23, 2004, which is incorporated herein by reference in its entirety.